

REGISTRATION FORM

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Name / First Name / Title

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Affiliation

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Address

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Phone / Fax

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E-Mail

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Signature

Please send this completed registration form: either as scan to susanne.kittner@ims.fraunhofer.de or by fax to +49 203 3783-153 until November 21st, 2016, at the latest.

Hotel Recommendation

By using the link below you will find some examples for hotels.
<http://www.ims.fraunhofer.de/content/dam/ims/en/documents/Contact/Hotels%20IMS%20englisch.pdf>

Please make your room reservation directly with the hotel of your choice.

Workshop Fee

- 450 € (Registration before November 7th, 2016)
- 550 € (Registration before November 21st, 2016)

The workshop fee includes lunches on both days and reception on November 29th, 2016. All participants will receive an USB memory stick with all presentations.

Cancellations

Half of the payment will be reimbursed for cancellations received before November 18th, 2016. Later cancellations will not be reimbured!

Terms of Payment

After reception of the registration form, an invoice will be sent to the participants and the fee has to be transferred under reference of the invoice number until November 25th, 2016, at the latest.
Payment by credit card is not possible.

Contact at Fraunhofer IMS:

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Location:

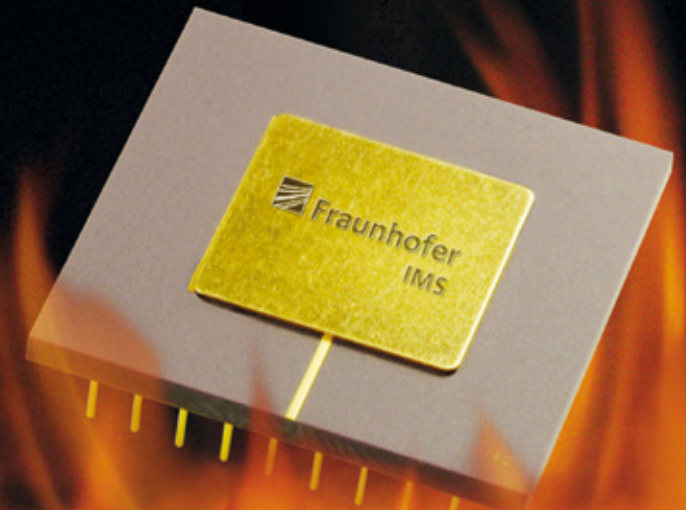
Fraunhofer-inHaus-Center
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47057 Duisburg
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How to find us

http://www.inhaus.fraunhofer.de/content/dam/inhaus/en/documents/Anfahrtsskizze_ims_inhaus_englisch_neu.pdf
Parking opportunities can be found on the nearby university car park in Carl-Benz-Strasse.

November 29th and 30th, 2016

FRAUNHOFER IMS WORKSHOP HIGH TEMPERATURE ELECTRONICS



Objectives and Scope

High temperature electronics is a continuously growing market in constant need of new technologies and concepts. Fraunhofer IMS hosts a workshop on HT electronics to provide a forum for industry and academia in this field. Follow interesting presentations on applications, circuit and system design, technologies and materials for HT applications and get in touch with users and technology providers.

Workshop Venue

The workshop will be held at the Fraunhofer-inHaus-Center in Duisburg, which is located near the Fraunhofer IMS.

Organizing Committee

Holger Kappert, Prof. Dr. Rainer Kokozinski
Assistance: Susanne Kittner

Miscellaneous

During the breaks there will be tabletop exhibits.
Reception will take place in the evening of November 29th, 2016. Further information will be given during the workshop.

	10:00	Welcome <i>Prof. Dr. Anton Grabmaier, Fraunhofer IMS</i>
APPLICATIONS/POWER	10:15	High temperature motor drive for aeronautic applications <i>Regis Meuret, Safran Electrical & Power</i>
	10:45	Power Modules for Power Electronics – Electrical and Lifetime Specifics <i>Andreas Schletz, Fraunhofer IISB</i>
	11:15	High Temperature SiC Intelligent Power Modules <i>Pierre Delatte, Cissoïd</i>
	12:00	Lunch
SENSORS	13:00	Using magnetoresistive sensors in high temperature applications <i>Dr. Rolf Slatter, Sensitec GmbH</i>
	13:30	Ceramics as heterogeneous integration platform for high temperature sensors <i>Dr.-Ing. Uwe Partsch, Fraunhofer IKTS</i>
	14:00	Design and characterization of a high-temperature pressure measurement system <i>Georg Gläser, IMMS Institut für Mikroelektronik- und Mechatronik-Systeme gGmbH</i>
	14:30	Break
SEMICONDUCTORS	15:15	Silicon-On-Insulator (SOI) based high temperature sensor devices and electronics <i>Dr. Andreas Goehlich, Holger Kappert, Fraunhofer IMS</i>
	15:45	Foundry CMOS Technologies for 175°C – Some like it hot! <i>Steffen Richter, X-FAB Semiconductor Foundries AG</i>
	17:30	Reception at the inHaus-Center

APPLICATION	9:00	Interconnection Technologies and Substrates for Automotive Electronics <i>Hubert Trageser, Conti Temic microelectronic GmbH</i>
PASSIVES	9:30	Thin film resistors for high temperature applications <i>Wolfgang Werner, VISHAY BCcomponents BEYSCHLAG GmbH</i>
	10:00	Break
	10:30	High temperature silicon capacitors and Integrated Passive Devices <i>Sébastien Lervez, IPDIA</i>
	11:00	No derating 200C DC-link capacitors <i>Jeff Lawler, W.L. Gore & Associates</i>
	11:30	Capacitor Technologies for High Temperature Applications <i>Ussama Margieh, AVX GmbH</i>
	12:00	Lunch
MATERIALS	13:00	Latent heat storage system for thermal management of power modules <i>Dr.-Ing. Andrej Novikov, Universität Rostock</i>
	13:30	Characterisation of High Temperature Component Interconnect Materials <i>Martin Wickham, National Physical Laboratory</i>
	14:00	End